BYK-P 9085

Processing additive with mold-release and surface-enhancing properties for Low Profile and Class A SMC.

Product Data

Composition
Combination of surface-active substances and polymers

Typical Properties
Values indicated in this data sheet describe typical properties and do not constitute specification limits.

Acid value :	88 mg KOH/g
Density (20 °C):	0.92 g/ml
Refractive index (20 °C):	1.47
Non-volatile matter (10 min., 150 °C):	> 97 %

Food Contact Legal Status
For the current food contact legal status, please contact our product safety department or visit www.byk.com for further information.

Applications

SMC

Special Features and Benefits
BYK-P 9085 was developed for Low Profile and Class A SMC systems. It stabilizes the compound and improves flow behavior. Because of its excellent mold-release properties, BYK-P 9085 completely replaces the traditional mold-release products. BYK-P 9085 improves the surface quality of the molded part. It also improves the paint adhesion and the bondability of the molded parts.

Recommended use
BYK-P 9085 is recommended for LP and Class A compounds.

Special Note
BYK-P 9085 affects thickening. An additional 10 % MgO may be needed to achieve thickening properties comparable to the Zn/Ca stearate system.

Recommended Levels

5-6 phr of the additive (as supplied) based upon total resin.
Optimal levels are determined through a series of laboratory tests.

Incorporation and Processing Instructions

Stir while adding after the UP resin and LP components have been homogenized.
Traditional mold-release products must be removed from the formulation.

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